

the system further including, on an atmosphere side of the insulating material, a planar plate arranged via dielectric at an earth-potential; and

the electromagnetic wave is applied to the planar plate to generate plasma in the vacuum chamber through reaction between the electromagnetic wave and the magnetic field.

Please add the following new claim:

--55. A plasma etching system in accordance with claim 33, wherein the insulating material includes one of quartz and aluminum oxide.--

REMARKS

A CPA has been submitted in order to obtain a filing date for this application which is subsequent to the November 29, 1999, so as to obtain the benefits of 35 U.S.C. §103(c) for this CPA.

By the present amendment, claim 33 has been amended in a manner which is considered to overcome the rejection thereof under 35 U.S.C. §112, second paragraph, it being noted that a new dependent claim 55 has been presented, reciting features deleted from claim 33 so that claims 33 and 55 should be considered to be in compliance with 35 U.S.C. §112, second paragraph.